Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	10084	29/592.1,605,830-832,842,846, 854.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:42
S2	150	microstimulator	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S3	0	S1 and S2	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:42
S4	45	(("5193539") or ("5193540") or ("5312439") or ("5350980") or ("5405367") or ("5750926") or ("5999848") or ("6051017") or ("6061596") or ("6164284") or ("6175764") or ("6181965") or ("6185452") or ("6208894") or ("6214032") or ("6232562") or ("6259937") or ("6315721") or ("6340839") or ("6516808") or ("65532253") or ("6553263") or ("6567703")).PN.	USPAT; USOCR; JPO; DERWENT	OR	OFF	2005/10/20 11:56
S5	5412	174/52.1,255,260,261.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:50
S6	1638	607/1-3,46,48-52,59-61.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:01
S7	353	600/302,554,377.cds.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:57
S8	116	128/877.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 11:57
S9	0	S2 and S5	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:01
S10	19	S2 and S4	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:01
S11	52	S2 and S6	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:07
S12	0	S2 and S7	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:02
S13	14	S10 and S11	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:02

S14	3721	circuit with substrate with trace	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:08
S15	0	S2 and S14	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S16	19000	microstimulator or stimulator	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S17	10	S1 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:05
S18	0	S14 and S17	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:03
S19	164	S1 and S14	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:04
S20	0	S5 and S9	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:04
S21	32	S5 and S19	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:04
S22	738	S6 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:05
S23	1	S14 and S22	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:06
S24	1	S5 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:06
S25	111	S7 and S16	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:07
S26	8	S22 and S25	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:07
S27	0	S11 and S14	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:08
S28	1	S11 and (circuit with trace)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 12:09

				 	r	
S29	56	("3617646" "3682160"	US-PGPUB;	OR	ON	2005/10/20 12:08
		"3995234" "4218772"	USPAT;			
		"4245178" "4321706"	USOCR			
i i		"4539531" "4553110"				
		"4553882" "4596022"				
		"4743789" "4814962"		İ		
		"4833427" "4916380"				
		"5053723" "5193539"				
		"5193540" "5324316"				
		"5405367" "5414741"		}		
		• •				
		"5438302" "5486794" "5506547" "5543754"	•			
		"5506547" "5543754"				
	•	"5643332" "5666279"				
		"5697076" "5766232"				
		"5798616" "5838203"				
		"5872703" "6016257"				
		"6046650" "6051017"		1		
]		"6064277" "6073050"		ĺ		
		"6215365" "6225873"				
		"6229406" "6239665"				
		"6255913" "6268777"				
		"6275539" "6456169"				
		"6462964" "6469587"				
		"6509805" "6538521"				
		"6539253" "6545554"				
	•	"6553263" "6593822"				
		"6593825" "6606006"				
		"6614288" "6621365").PN.				
C30			I ICDAT:	00	ON	2005/10/20 12:10
S30	6	S2 and S29	USPAT;	OR	ON	2005/10/20 12:10
			JPO;			
			DERWENT			
S31	0	S30 and (circuit with trace)	USPAT;	OR	ON	2005/10/20 12:09
	_	(0.00.00.00.00.00.00.00.00.00.00.00.00.0	JPO;			-,00,-0,00 02.00
ŀ			DERWENT			
S32	8	He-Tom-Xiaohai.in. or	USPAT;	OR	ON	2005/10/20 12:11
		Haller-Matthew-I.in. or	JPO;			
		Parramon-Jordi.in. or	DERWENT			
		Marnfeldt-Goran-N.in.				
S33	0	C2 and C9	USPAT;	OB	ON	2005/10/20 12:11
333	U	S2 and S8	1	OR	ON	2005/10/20 12:11
			JPO;			
			DERWENT			
S34	54423	(substrate with pad)	USPAT;	OR	ON	2005/10/20 14:06
		,	JPO;		T	
			DERWENT			
S37	7712	(integrated adj circuit) with	USPAT;	OR	ON	2005/10/20 14:09
	i	((conductive or metal) adj layer)	JPO;			
	į		DERWENT			
S38	11132	connect\$3 with substrate with	USPAT;	OR	ON	2005/10/20 14:08
٥٥٥	11112		JPO;	UN	UN	2003/10/20 17.00
		(integrated adj circuit)				
			DERWENT			

S39	266	S34 and S37 and S38	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:08
S40	453	((conductive or metal) adj layer) with trace with pad	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:10
S41	18	S39 and S40	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:09
S42	39927	((insulat\$3 or dielectric) adj layer) with ((conductive or metal) adj layer)	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:10
S43	11	S41 and S42	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:27
S44	8400	257/723,724,737,738,782-786. ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:28
S45	10	S37 and S38 and S40 and S44	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:30
S46	4377	361/735,794,683,810,777,778, 792.ccls.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:30
S47	2	S37 and S38 and S40 and S46	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:34
S48	15657131	JP 0616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S49	0	JP-0616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S50	0	JP-40616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S51	0	JP-616919-\$.did.	USPAT; JPO; DERWENT	OR	ON	2005/10/20 14:35
S52	444074	(integrated adj circuit) or (printed adj circiut)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:16
S53	1	trace with (mount\$3 adj pad) with (interconnect adj pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:06
S54	8250	trace with pad	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:06

S55	642	((integrated adj circuit) or (printed adj circiut)) with (trace with pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:17
S56	7	(mount\$3 adj pad) with (interconnect adj pad)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:07
S57	0	(mount\$3 adj pad) with (interconnect adj pad) with (conductive adj layer)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:07
S58	642	((integrated adj circuit) or (printed adj circiut)) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:19
S59	0	((integrated adj circuit) with (printed adj circiut)) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:19
S60	74	((integrated adj circuit) with (printed adj circuit)) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:20
S61	7	(((integrated adj circuit) with (printed adj circuit)) with (trace with pad\$1)) same (insulat\$3 or dielectric)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:53
S62	642	(integrated adj circuit) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:32
S63	0	(integrated adj circuit) near (printed adj circiut)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:35
S64	1739	(integrated adj circuit) near (printed adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:35
S65	22	S62 and S64	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:35
S66	13	("4907067" "5223741" "5229727" "5270673" "5389904" "5753972" "5900312" "6124636" "6147389" "6172412" "6248959" "6271579" "6509531").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 07:50
S67	1115	(printed adj circuit) with (trace with pad\$1)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:54
S68	31	S64 and S67	USPAT; JPO; DERWENT	OR	ON	2005/10/24 07:54

S69	0	trace near pad near insualtion	USPAT; JPO; DERWENT	OR	ON	2005/10/24 08:56
S70	11	trace near pad near insulat\$3	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:00
S71	1	(US-6511865-\$).did.	USPAT	OR	ON	2005/10/24 09:00
S72	1	S71 and insulat\$3	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:00
S73	250	process\$3 near (integrated adj circuit) near wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:29
S74	0	post near process\$3 near (integrated adj circuit) near wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:16
S75	26226	(post adj process\$3)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:27
S76	2	S73 and S75	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:24
S77	5	("5732209" "5926027" "6032268" "6162652" "6400173").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 09:26
S78	0	S75 and S77	US-PGPUB; USPAT; USOCR	OR	ON	2005/10/24 09:26
S79	6	(post adj process\$3) near IC	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:27
S80	0	(post adj process\$3) near (integrated adj circuit) near wafer	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:29
S81	9	(post adj process\$3) with ((integrated adj circuit) near wafer)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:31
S82	8	(post adj process\$3) near (integrated adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:35
S83	133	(post adj process\$3) with (integrated adj circuit)	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:35
S84	0	(post adj process\$3) with (integrated adj circuit) with web	USPAT; JPO; DERWENT	OR	ON	2005/10/24 09:36

S85	23	(post adj process\$3) with (integrated adj circuit) with wafer	USPAT; JPO;	OR	ON	2005/10/24 09:36
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IEEE STO IEEE Standard

1. RF telemetry powering and control of hermetically sealed integrated sens actuators

Akin, T.; Ziaie, B.; Najafi, K.;

Solid-State Sensor and Actuator Workshop, 1990. 4th Technical Digest., IEEE

4-7 June 1990 Page(s):145 - 148

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